

See your future in our Direct Write Exposure Solution

Direct Write Exposure Sytems





Ushio's DE-2 and DE-8



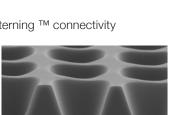




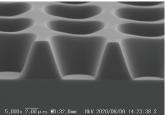
DE-2 2µm L/S Direct Write Exposure System

DE-2 W300 for 300mm (12") Wafer DE-2 P600 for 600 × 600mm Panel December 2021 Debut

- Maskless Direct Imaging for Fan-Out WLP & PLP and High Precision Packaging
- Minimum Line/Space = 2/2µm imaging capability
- Overlay accuracy ≤ 1µm
- Optional Deca's Adaptive Patterning ™ connectivity



L/S 2/2µm Liquid Photo-sensitive Resist 7µm thick



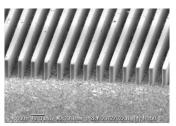
Via opening 5µm dia. 10µm Pitch Liquid Photo-sensitive Polyimide 7µm thick



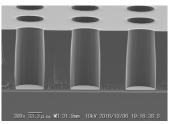
DE-8 Direct Write Exposure System for FO-WLP/PLP

DE-8 W300 for 300mm (12") Wafer DE-8 P600 for 600 x 600mm Panel

- Maskless Direct Imaging for FAN-OUT WLP & PLP
- Minimum Line/Space = 8/8µm imaging capability
- Overlay accuracy ≤ 7µm
- Optional Deca's Adaptive Patterning ™ connectivity



L/S 5/5µm Dry Film Resist 15µm thick



Opening 70µm dia. 140µm Pitch Dry Film Resist 160µm thick



As a product moves through the manufacturing process, Adaptive Patterning™ (AP) customizes each lithographic layer on a device-by-device basis to ensure the highest possible yield.

Create nominal design with instructions for AP (one-time for each new product)

. DESIGN



2. ADAPT Execute real-time design optimization during



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